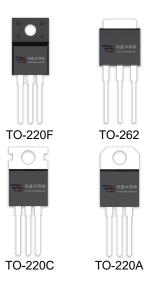
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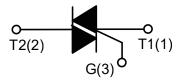
#### **DESCRIPTION:**

With high ability to withstand the shock loading of large current, T1630-600W series triacs provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load.



#### **MAIN FEATURES**

Symbol	Symbol Value	
I <sub>T(RMS)</sub>	16	А
V <sub>DRM</sub> /V <sub>RRM</sub>	600/800/1200	V



#### **ABSOLUTE MAXIMUM RATINGS**

Р	arameter	Symbol	Value	Unit
Storage junction temperature range		T <sub>stg</sub>	-40-150	$^{\circ}$
Operating junction temperature range		Tj	-40-125	$^{\circ}$
Repetitive peak off-state voltage (T <sub>j</sub> =25℃)		V <sub>DRM</sub>	600/800/1200	V
Repetitive peak reverse voltage (T <sub>j</sub> =25℃)		V <sub>RRM</sub>	600/800/1200	V
Non repetitive surge peak Off-state voltage		V <sub>DSM</sub>	V <sub>DRM</sub> +100	V
Non repetitive peak reverse voltage		V <sub>RSM</sub>	V <sub>RRM</sub> +100	V
$ \begin{array}{c} \text{TO-220A(Ins)/} \\ \text{TO-220F(Ins)} \ (\text{T}_{\text{C}}\text{=}75^{\circ}\text{C}) \\ \text{TO-220A(Non-Ins)/} \\ \text{TO-220C} \ (\text{T}_{\text{C}}\text{=}95^{\circ}\text{C}) \\ \text{TO-262} \ (\text{T}_{\text{C}}\text{=}70^{\circ}\text{C}) \\ \end{array} $		I <sub>T(RMS)</sub>	16	А
Non repetitive surge peak on-state current (full cycle, F=50Hz)		I <sub>TSM</sub>	160	А

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I <sup>2</sup> t value for fusing (tp=10ms)	l <sup>2</sup> t	128	A <sup>2</sup> s
Critical rate of rise of on-state current (I <sub>G</sub> =2×I <sub>GT</sub> )	dl/dt	50	A/µs
Peak gate current	I <sub>GM</sub>	4	Α
Average gate power dissipation	P <sub>G(AV)</sub>	1	W
Peak gate power	P <sub>GM</sub>	5	W

# **ELECTRICAL CHARACTERISTICS** ( $T_j$ =25 $^{\circ}$ C unless otherwise specified)

## 3 Quadrants

Symbol	Test Condition	Quadrant		Value				Unit
				BW	CW	sw	TW	Offic
lgт	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	I - II -III	MAX	50	35	10	5	mA
V <sub>G</sub> T	VD-12V KL-3312	I - II -III	MAX	1.3				V
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125$ °C RL = 3.3KΩ	I - II -III	MIN	0.2			V	
lι	I <sub>G</sub> =1.2I <sub>GT</sub>	I -III	MAX	70	50	30	15	mΛ
		II	IVIAA	80	60	40	20	mA
Ін	I <sub>T</sub> =100mA		MAX	60	40	25	15	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	1000	500	200	100	V/µs

## 4 Quadrants

Symbol	Test Condition Qu	Quadrant	Quadrant	Va	Unit	
		Quadrant		В	С	Onne
lgт		I - II -III	MAN	50	25	mA
	V <sub>D</sub> =12V R <sub>L</sub> =33Ω	IV	IVIAA	MAX 70 50	50	
V <sub>G</sub> T		ALL	MAX	1.5		V
V <sub>GD</sub>	$V_D = V_{DRM} T_j = 125^{\circ}C$ $R_L = 3.3 K\Omega$	ALL	MIN	0.2		V
IL	I <sub>G</sub> =1.2I <sub>GT</sub>	I -III-IV	MAX	70	50	- mA
		II	IVIAA	100	80	IIIA
Ін	I <sub>T</sub> =100mA		MAX	60	40	mA
dV/dt	V <sub>D</sub> =2/3V <sub>DRM</sub> Gate Open T <sub>j</sub> =125℃		MIN	500	200	V/µs

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## **STATIC CHARACTERISTICS**

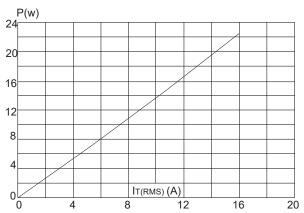
Cymbol	Parameter		V	Unit		
Symbol			-600V	-800V	-1200V	Offic
V <sub>TM</sub>	I <sub>TM</sub> =22.5A tp=380μs	T <sub>j</sub> =25℃	1.5			V
I <sub>DRM</sub>	V <sub>D</sub> =V <sub>DRM</sub> V <sub>R</sub> =V <sub>RRM</sub>	T <sub>j</sub> =25℃	5	5	10	μA
I <sub>RRM</sub>		T <sub>j</sub> =125℃	1	1	2	mA

## **THERMAL RESISTANCES**

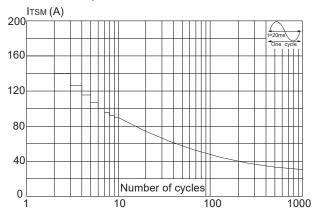
Symbol	Parameter		Value	Unit
Rth(j-c)	junction to case(AC)	TO-220A(Ins)	2.1	°C/W
		TO-220A(Non-Ins)/ TO-220C	1.2	
		TO-220F(Ins)	2.3	
		TO-262	2.5	



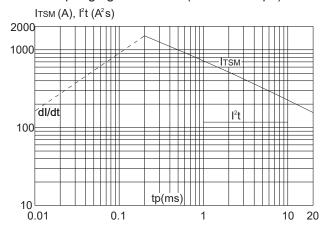
**FIG.1** Maximum power dissipation versus RMS on-state current



**FIG.3:** Surge peak on-state current versus number of cycles



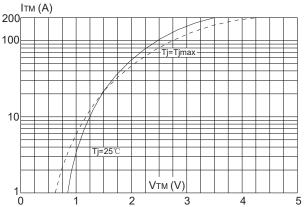
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<20ms, and corresponging value of I<sup>2</sup>t (dI/dt < 50A/µs)



**FIG.2:** RMS on-state current versus case temperature



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature

